

**April 2013** 

# FGY75N60SMD

# 600 V, 75 A Field Stop IGBT

## **Features**

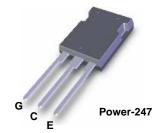
- · High Current Capability
- Low Saturation Voltage:  $V_{CE(sat)} = 1.9 V @ I_C = 75 A$
- High Input Impedance
- Fast Switching: E<sub>OFF</sub> = 10 uJ/A
- RoHS Compliant

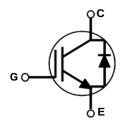
## **General Description**

Using novel field stop IGBT technology, Fairchild®'s new series of field stop 2<sup>nd</sup> generation IGBTs offer the optimum performance for solar inverter, UPS, welder and PFC applications where low conduction and switching losses are essential.

## **Applications**

· Solar Inverter, UPS, Welder, PFC





# **Absolute Maximum Ratings**

Symbol	Description		Ratings	Unit
V <sub>CES</sub>	Collector to Emitter Voltage		600	V
$V_{GES}$	Gate to Emitter Voltage		± 20	V
I <sub>C</sub>	Collector Current	@ T <sub>C</sub> = 25°C	150	А
10	Collector Current	@ T <sub>C</sub> = 100°C	75	А
I <sub>CM (1)</sub>	Pulsed Collector Current @ T <sub>C</sub> = 25°C		225	А
I <sub>F</sub>	Diode Forward Current	$^{\circ}$ T <sub>C</sub> = 25 $^{\circ}$ C	75	А
	Diode Forward Current	$@ T_C = 100^{\circ}C$	50	А
I <sub>FM (1)</sub>	Pulsed Diode Maximum Forward Current		225	A
P <sub>D</sub>	Maximum Power Dissipation	@ T <sub>C</sub> = 25°C	750	W
י ט	Maximum Power Dissipation	$@ T_C = 100^{\circ}C$	375	W
T <sub>J</sub>	Operating Junction Temperature		-55 to +175	°C
T <sub>stg</sub>	Storage Temperature Range		-55 to +175	°C
TL	Maximum Lead Temp. for soldering Purposes, 1/8" from case for 5 seconds		300	°C

### Notes

1: Repetitive rating: Pulse width limited by max. junction temperature.

## **Thermal Characteristics**

Symbol	Parameter	Тур.	Max.	Unit
$R_{\theta JC}(IGBT)$	Thermal Resistance, Junction to Case	-	0.2	°C/W
$R_{\theta JC}(Diode)$	Thermal Resistance, Junction to Case	-	0.7	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	-	40	°C/W

# **Package Marking and Ordering Information**

Device Marking Device		Package	Packaging Type	Qty per Tube	
FGY75N60SMD	N60SMD FGY75N60SMD Power-247		Tube	30ea	

# Electrical Characteristics of the IGBT T<sub>C</sub> = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Charac	eteristics		·			
BV <sub>CES</sub>	Collector to Emitter Breakdown Voltage	$V_{GE} = 0V, I_{C} = 250\mu A$	600	-	-	V
$\frac{\Delta BV_{CES}}{\Delta T_J}$	Temperature Coefficient of Breakdown Voltage	$V_{GE} = 0V, I_C = 250\mu A$	-	0.67	-	V/°C
I <sub>CES</sub>	Collector Cut-Off Current	$V_{CE} = V_{CES}, V_{GE} = 0V$	-	-	250	μА
I <sub>GES</sub>	G-E Leakage Current	$V_{GE} = V_{GES}, V_{CE} = 0V$	-	-	±400	nA
On Charac	teristics					
V <sub>GE(th)</sub>	G-E Threshold Voltage	$I_{C} = 250 \mu A, V_{CE} = V_{GE}$	3.5	5.0	6.5	V
- (* )		I <sub>C</sub> = 75A, V <sub>GE</sub> = 15V	-	1.90	2.50	V
V <sub>CE(sat)</sub>	Collector to Emitter Saturation Voltage	I <sub>C</sub> = 75A, V <sub>GE</sub> = 15V, T <sub>C</sub> = 175°C	-	2.14	-	V
Dynamic C	Characteristics					
C <sub>ies</sub>	Input Capacitance		-	3800	-	pF
C <sub>oes</sub>	Output Capacitance	$V_{CE} = 30V_{,} V_{GE} = 0V_{,}$ f = 1MHz	-	390	-	pF
C <sub>res</sub>	Reverse Transfer Capacitance	1 = 11/11/12	-	105	-	pF
Switching	Characteristics					
t <sub>d(on)</sub>	Turn-On Delay Time		-	24	32	ns
t <sub>r</sub>	Rise Time		-	56	73	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	V <sub>CC</sub> = 400V, I <sub>C</sub> = 75A,	-	136	177	ns
t <sub>f</sub>	Fall Time	$R_G = 3\Omega, V_{GE} = 15V,$	-	22	29	ns
E <sub>on</sub>	Turn-On Switching Loss	Inductive Load, T <sub>C</sub> = 25°C	-	2.3	2.99	mJ
E <sub>off</sub>	Turn-Off Switching Loss		-	0.77	1.00	mJ
E <sub>ts</sub>	Total Switching Loss		-	3.07	3.99	mJ
t <sub>d(on)</sub>	Turn-On Delay Time		-	23	-	ns
t <sub>r</sub>	Rise Time		-	53	-	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{CC} = 400V, I_{C} = 75A,$ $R_{G} = 3\Omega, V_{GE} = 15V,$	-	146	-	ns
t <sub>f</sub>	Fall Time		-	15	-	ns
E <sub>on</sub>	Turn-On Switching Loss	Inductive Load, T <sub>C</sub> = 175°C	-	3.60	-	mJ
E <sub>off</sub>	Turn-Off Switching Loss		-	1.11	-	mJ
E <sub>ts</sub>	Total Switching Loss		-	4.71	-	mJ

# Electrical Characteristics of the IGBT $T_C = 25^{\circ}C$ unless otherwise noted

Qg	Total Gate Charge		-	248	370	nC
$Q_{ge}$	Gate to Emitter Charge	$V_{CE} = 400V, I_{C} = 75A,$ $V_{GE} = 15V$	-	28	42	nC
Q <sub>gc</sub>	Gate to Collector Charge	VGE = 10V	-	129	195	nC

# Electrical Characteristics of the Diode $T_C = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Test Conditions		Min.	Тур.	Max	Unit
V <sub>FM</sub>	Diode Forward Voltage	I <sub>F</sub> = 50A	$T_{\rm C} = 25^{\rm o}{\rm C}$	-	1.75	2.1	V
			$T_{\rm C} = 175^{\rm o}{\rm C}$	-	1.35	-	
E <sub>rec</sub>	Reverse Recovery Energy	$I_F = 50A$ , $dI_F/dt = 200A/\mu s$ $V_R = 400V$	$T_{\rm C} = 175^{\rm o}{\rm C}$	-	0.14	-	mJ
t	Diode Reverse Recovery Time  Q <sub>rr</sub> Diode Reverse Recovery Charge		$T_{\rm C} = 25^{\rm o}{\rm C}$	-	41	55	ns
ALL STEEL			$T_{\rm C} = 175^{\rm o}{\rm C}$	=	126	-	1
Q			$T_{\rm C} = 25^{\rm o}{\rm C}$	-	81	115	nC
			$T_{\rm C} = 175^{\rm o}{\rm C}$	=	736	-	]

Figure 1. Typical Output Characteristics

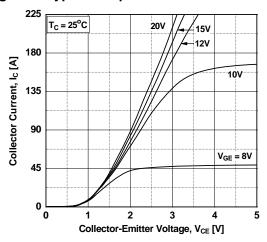


Figure 3. Typical Saturation Voltage Characteristics

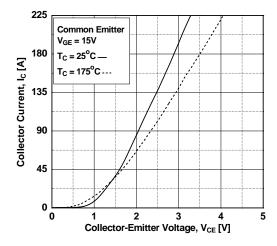
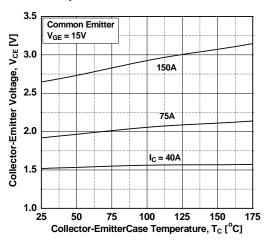


Figure 5. Saturation Voltage vs. Case
Temperature at Variant Current Level



**Figure 2. Typical Output Characteristics** 

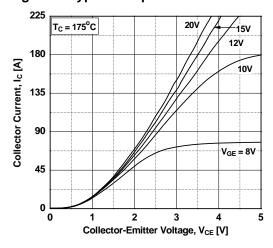


Figure 4. Transfer Characteristics

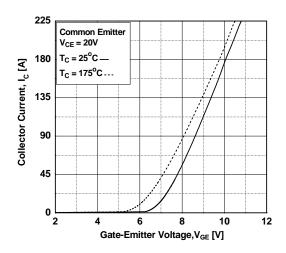


Figure 6. Saturation Voltage vs.  $V_{GE}$ 

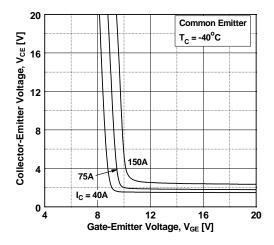


Figure 7. Saturation Voltage vs. V<sub>GE</sub>

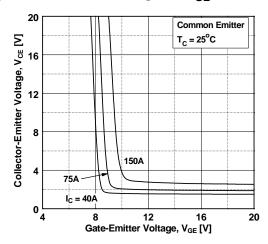


Figure 9. Capacitance Characteristics

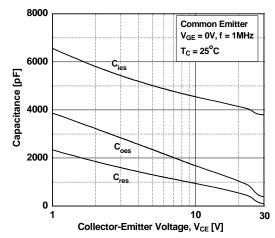


Figure 11. Turn-off Characteristics vs.
Gate Resistance

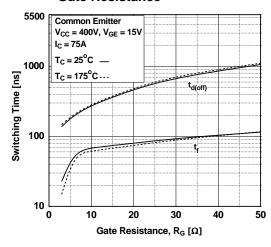


Figure 8. Saturation Voltage vs. V<sub>GE</sub>

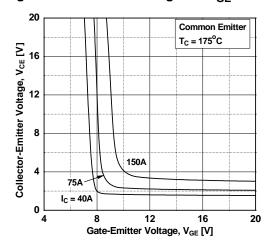


Figure 10. Gate charge Characteristics

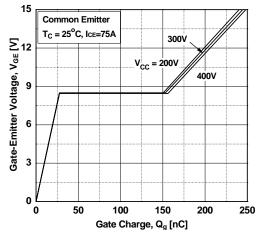


Figure 12. Turn-on Characteristics vs.
Gate Resistance

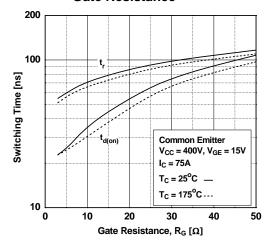


Figure 13. Turn-off Characteristics vs. Collector Current

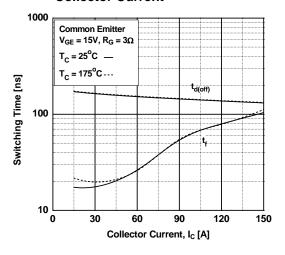


Figure 14. Turn-on Characteristics vs. Collector Current

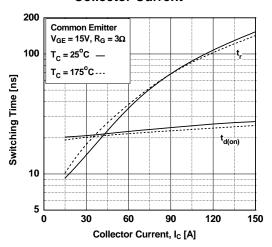


Figure 15. Switching Loss vs. Collector Current

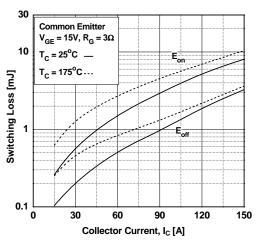


Figure 16. Switching Loss vs. Gate Resistance

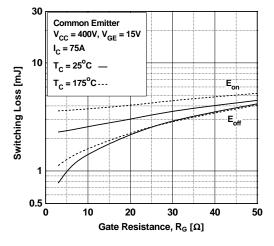


Figure 17. SOA Characteristics

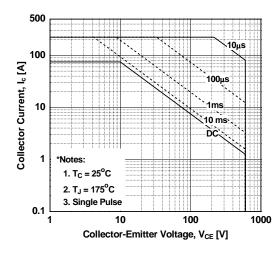
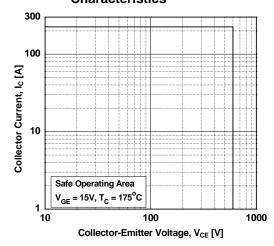


Figure 18. Turn off Switching SOA Characteristics



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Figure 19. Current Derating

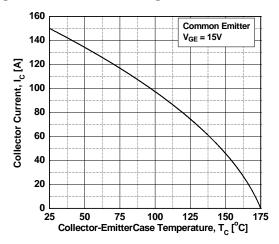


Figure 20. Load Current vs. Frequency

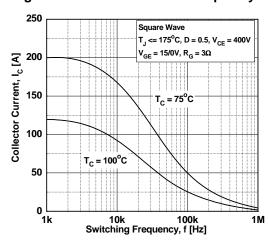


Figure 21. Forward Characteristics

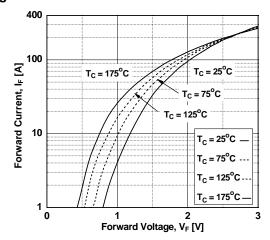


Figure 22. Reverse Current

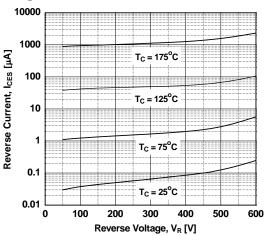


Figure 23. Stored Charge

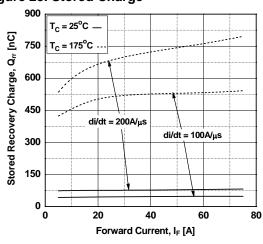


Figure 24. Reverse Recovery Current

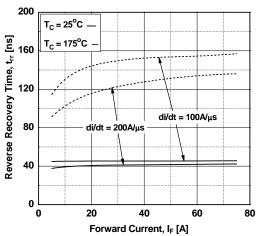


Figure 25. Transient Thermal Impedance of IGBT

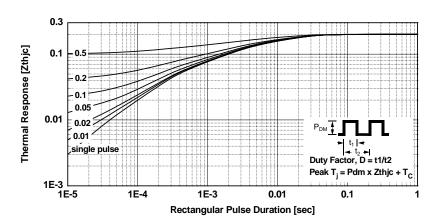
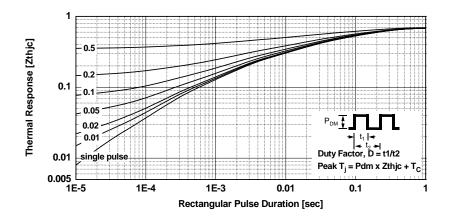
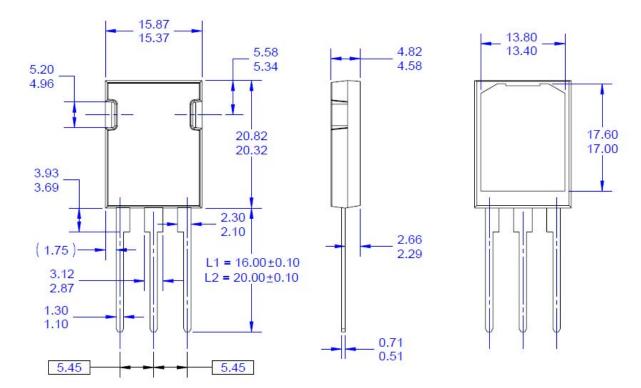


Figure 26. Transient Thermal Impedance of Diode



## **Mechanical Dimensions**

# TO2-247D03



### NOTES:

- A. THIS PACKAGE DOES NOT CONFORM TO ANY STANDARDS.
- ANT STANDARDS.

  B. ALL DIMENSIONS ARE IN MILLIMETERS.
  C. DIMENSIONS ARE EXCLUSIVE OF BURRS,
  MOLD FLASH AND TIE BAR PROTRUSIONS.
  E. DIMENSION AND TOLERANCE AS PER ASME
- Y14.5-1994.
- F. DRAWING FILE NAME: TO247D03REV1

**Dimensions in Millimeters** 





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Datasheet Identification	Product Status	Definition
Advance Information	Formative / In Design	Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
Obsolete	Not In Production	Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.

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